

Low Dropout Regulators

Description

The SL73A series is a set of three-terminal low power high voltage regulators implemented in CMOS technology. They allow input voltages as high as 20V. They are available with several fixed output voltages ranging from 2.1V to 9.0V. Because of the low power dissipation, SL73A series are widely used in a variety of equipment such as audio device, video device, communication device and so on.

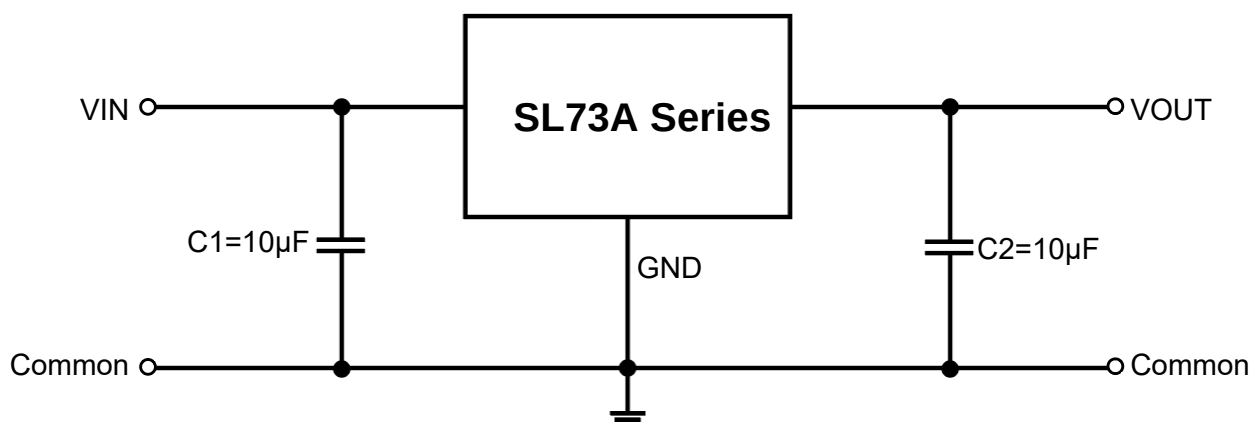
Features

- High Input Voltage Range: up to 20V
- Maximum Output Current: 300mA
- FixedStandard Fixed Output Voltage Options: 2.8V,3V,3.3V,3.6V,4V,4.4V,5V,9V
- Low Quiescent current: 1.5 μ A
- PSRR=dB@1KHz
- Low Dropout: 300mV(Max.)@100mA
- Low Output Voltage Accuracy: $\pm 2\%$
- Low Power Consumption
- Low Temperature Coefficient
- Available Packages: SOT-23、SOT-23-3、SOT-89、SOT-23-5

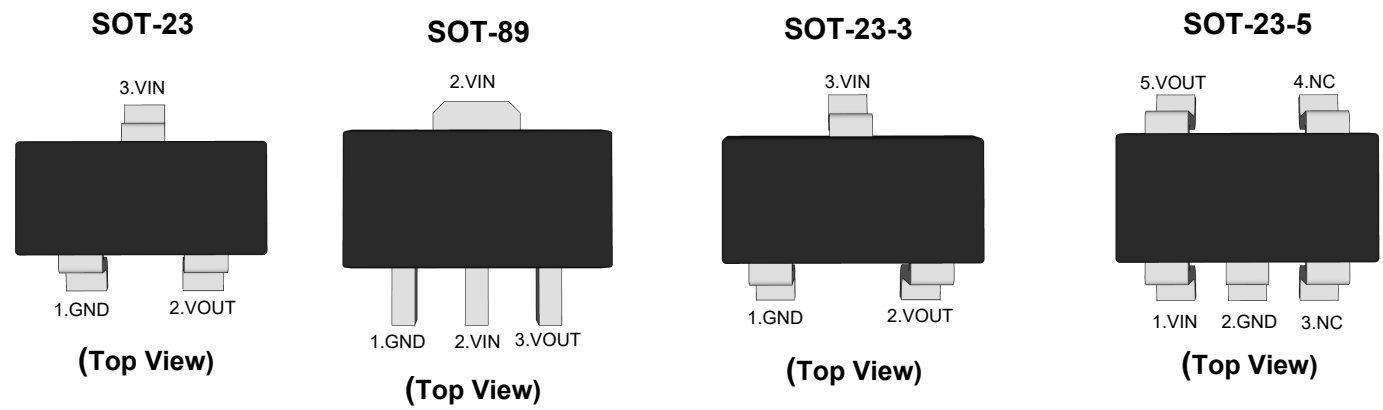
Applications

- Battery-Powered Equipment
- Ultra Low Power Microcontrollers
- Notebook Computers

Typical Application Circuit



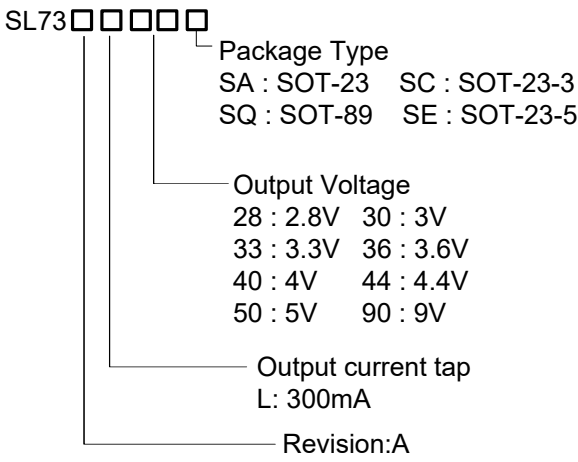
Pin Distribution



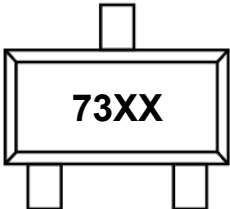
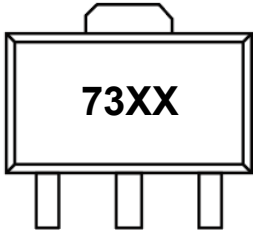
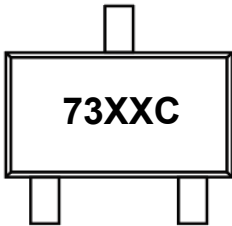
Functional Pin Description

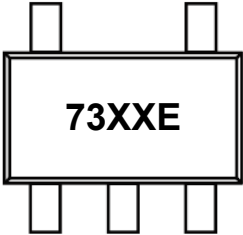
Pin Name	Pin Function
NC	NO Connected
GND	Ground
VOUT	Output Voltage
VIN	Power Input Voltage

Ordering Information

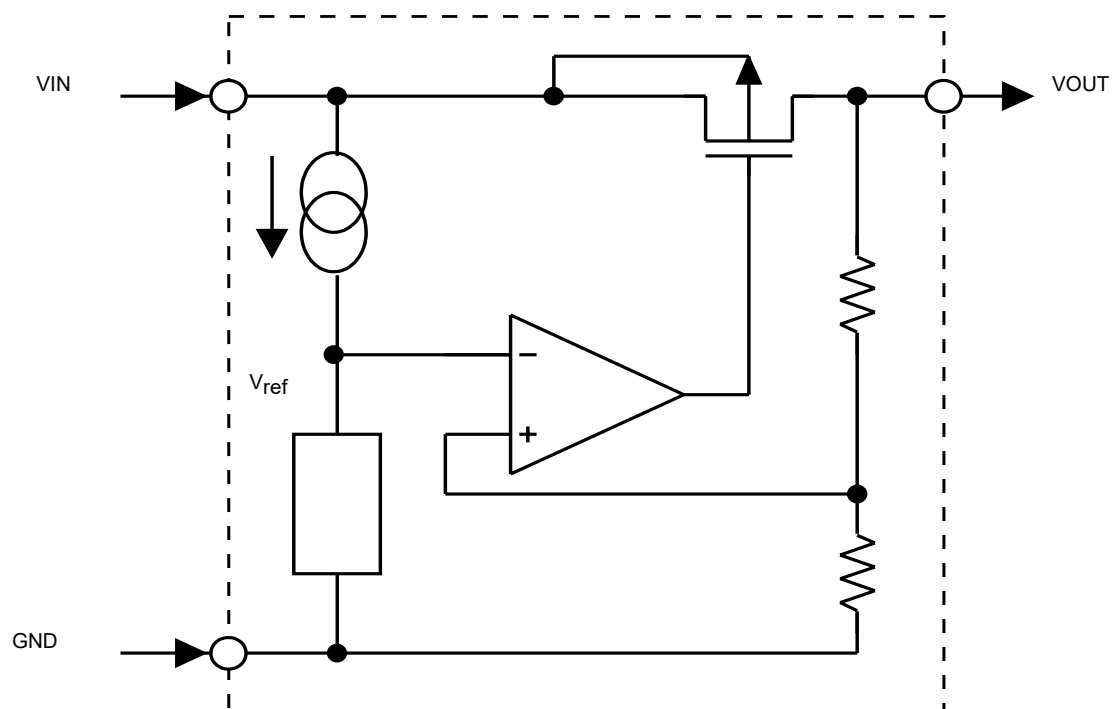


Ordering Information Continue

Orderable Device	Package	Reel (inch)	Package Qty (PCS)	Eco Plan ^{Note}	MSL Level	Marking Code
SL73AL28SA	SOT-23	7	3000	RoHS & Green	MSL1	 XX:Output Voltage e.g. 30:3.0V
SL73AL30SA						
SL73AL33SA						
SL73AL36SA						
SL73AL40SA						
SL73AL44SA						
SL73AL50SA						
SL73AL28SQ	SOT-89	7	1000	RoHS & Green	MSL1	 XX:Output Voltage e.g. 30:3.0V
SL73AL30SQ						
SL73AL33SQ						
SL73AL36SQ						
SL73AL40SQ						
SL73AL44SQ						
SL73AL50SQ						
SL73AL28SC	SOT-23-3	7	3000	RoHS & Green	MSL3	 XX:Output Voltage e.g. 30:3.0V
SL73AL30SC						
SL73AL33SC						
SL73AL36SC						
SL73AL40SC						
SL73AL44SC						
SL73AL50SC						
SL73AL90SC						

SL73AL28SE	SOT-23-5	7	3000	RoHS & Green	MSL3	 73XXE XX:Output Voltage e.g. 30:3.0V
SL73AL30SE						
SL73AL33SE						
SL73AL36SE						
SL73AL40SE						
SL73AL44SE						
SL73AL50SE						
SL73AL90SE						

Note:
RoHS: SL defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials.
Green: SL defines "Green" to mean Halogen-Free and Antimony-Free.

Function Block Diagram

Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter		Value	Unit
Supply Voltage		-0.3 ~ +22	V
Power Dissipation	SOT-23	180	mW
	SOT-23-3	200	mW
	SOT-23-5	200	mW
	SOT-89	500	mW
Thermal Resistance, Junction-to-Ambient	SOT-23	550	°C/W
	SOT-23-3	500	°C/W
	SOT-23-5	500	°C/W
	SOT-89	200	°C/W
Operating Ambient Temperature		-40 ~ +85	°C
Storage temperature range		-50 ~ +125	°C
ESD Voltage	HBM	2	KV

Note: 1. Exceed these limits to damage to the device, exposure to absolute maximum rating conditions may affect the reliability of the chip.

Recommended Operating Conditions

Parameter	Value	Unit
Supply Voltage	20	V
Maximum Output Current	300	mA
Operating Ambient Temperature	-40 ~ +85	°C

Electrical Characteristics

($V_{IN}=V_{OUT}+2$, $C_{IN}=10\mu F$, $C_{OUT}=10\mu F$, $T_A=25^\circ C$, unless otherwise noted.)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Input Voltage	V_{IN}		--	--	20	V
Output Voltage Accuracy	ΔV_{OUT}	$I_{OUT}=10mA$	-2	--	+2	%
Max. Output Current	I_{OUT}		300	--	--	mA
Quiescent Current	I_Q	$I_{OUT}=0mA$	--	1.5	3	μA
Dropout Voltage ^{Note1}	V_{DROP}	$2.8V \leq V_{OUT} < 3.0V$, $I_{OUT}=10mA$	--	30	55	mV
		$3.0V \leq V_{OUT} < 3.3V$, $I_{OUT}=100mA$	--	210	300	
		$3.3V \leq V_{OUT} < 3.6V$, $I_{OUT}=100mA$	--	195	300	
		$3.6V \leq V_{OUT} < 4.0V$, $I_{OUT}=100mA$	--	180	300	
		$4.0V \leq V_{OUT} < 4.4V$, $I_{OUT}=100mA$	--	170	300	
		$4.4V \leq V_{OUT} < 5.0V$, $I_{OUT}=100mA$	--	160	300	
		$5.0V \leq V_{OUT} < 9.0V$, $I_{OUT}=100mA$	--	150	300	
		$9.0V \leq V_{OUT}$, $I_{OUT}=100mA$	--	130	300	
Line Regulation	ΔV_{LINE}	$V_{IN}=V_{OUT}+2$ to 20V, $I_{OUT}=1mA$	--	--	0.2	%/V
Load Regulation	ΔV_{LOAD}	$1mA < I_{OUT} < 300mA$	--	37	100	mV
Short Current	I_{SHORT}	$V_{OUT}=0V$	--	250	--	mA
Limit Current	I_{LIMIT}	$V_{IN}=V_{OUT} + 2V$, $I_{OUT}=1mA$	--	530	--	mA
Power Supply Rejection Ratio	PSRR	$V_{OUT}=3V$, $I_{OUT}=100mA$, $f=1KHz$	--	33	--	dB
VOUT Temperature Coefficient	$\frac{\Delta V_{OUT}}{V_{OUT} \times \Delta T_A}$	$V_{IN}=V_{OUT}+2V$, $I_{OUT}=10mA$ $-40^\circ C \leq T_A \leq 85^\circ C$	--	100	--	ppm/ $^\circ C$

Note 1. The dropout voltage is defined as $V_{IN} - V_{OUT}$, when V_{OUT} is 98% of the normal value of V_{OUT} .

Functional Description

Input Capacitor

A 1μF ceramic capacitor is recommended to connect between VIN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and less noise. For PCB layout, a wide copper trace is required for both VIN and GND.

Output Capacitor

An output capacitor is required for the stability of the LDO. The recommended minimum output capacitance is 10μF, ceramic capacitor is recommended, and temperature characteristics are X7R or X5R. Higher capacitance values help to improve load/line transient response. The output capacitance may be increased to keep low undershoot/overshoot. Place output capacitor as close as possible to VOUT and GND pins.

Thermal Considerations

For continuous operation, do not exceed absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated by the following formula :

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / R_{\theta JA}$$

Where $T_{J(MAX)}$ is the maximum operation junction temperature 125 °C, T_A is the ambient temperature and the $R_{\theta JA}$ is the junction to ambient thermal resistance.

The power dissipation definition in device is :

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} + V_{IN} \times I_Q$$

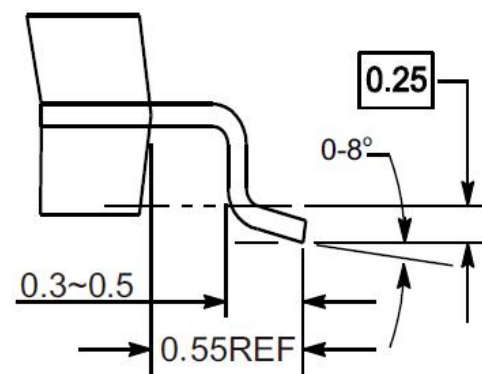
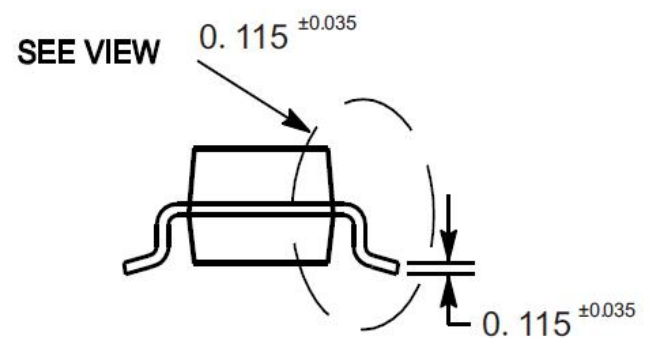
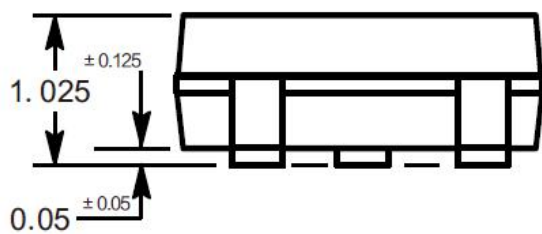
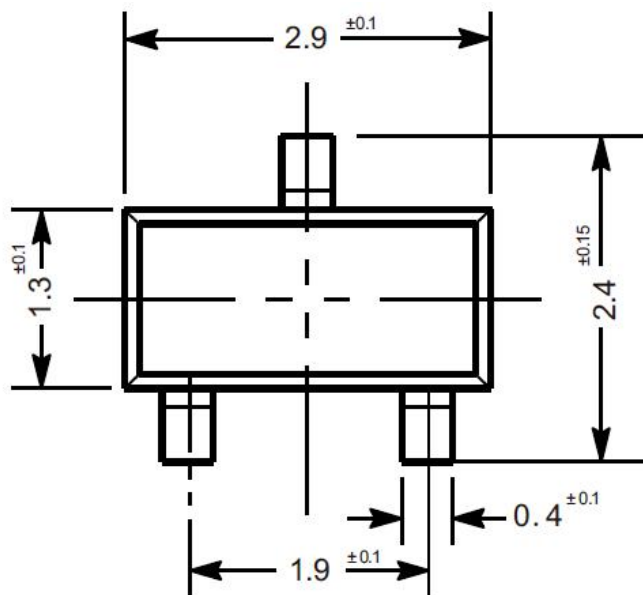
Layout Consideration

By placing input and output capacitors on the same side of the PCB as the LDO, and placing them as close as is practical to the package can achieve the best performance. The ground connections for input and output capacitors must be back to the SL73A Series ground pin using as wide and as short of a copper trace as is practical. Connections using long trace lengths, narrow trace widths, and connections through via must be avoided. These add parasitic inductances and resistance that results in worse performance especially during transient conditions.

Package Outline

SOT-23

Dimensions in mm

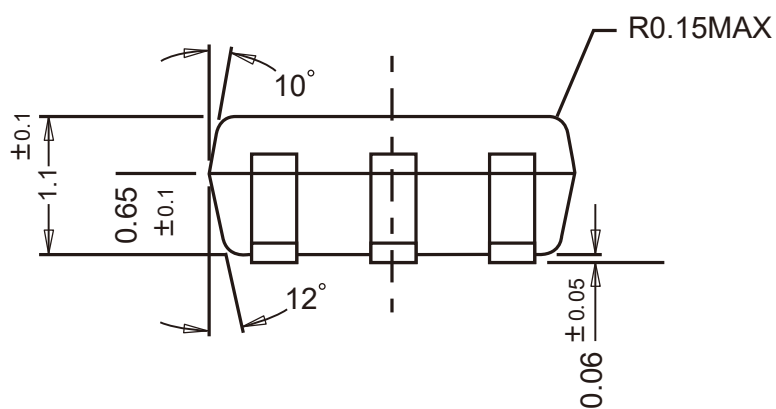
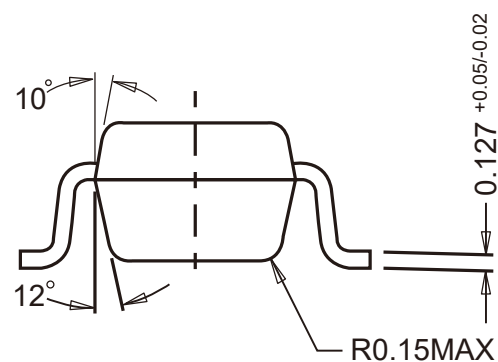
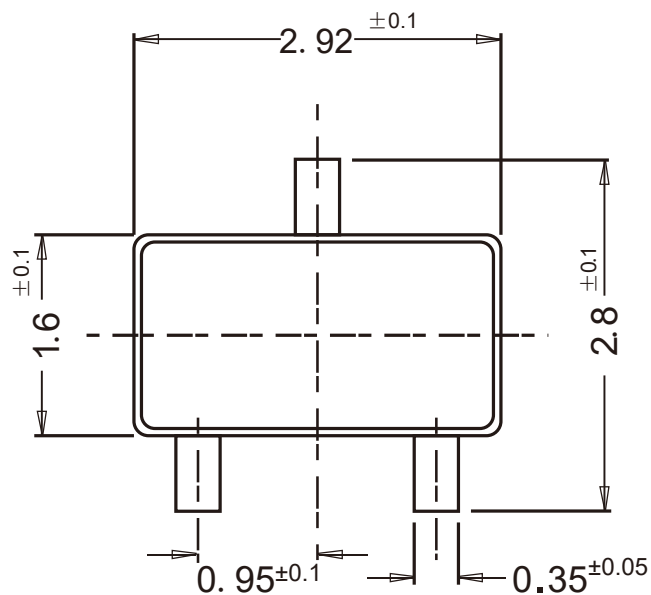


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Package Outline

SOT-23-3

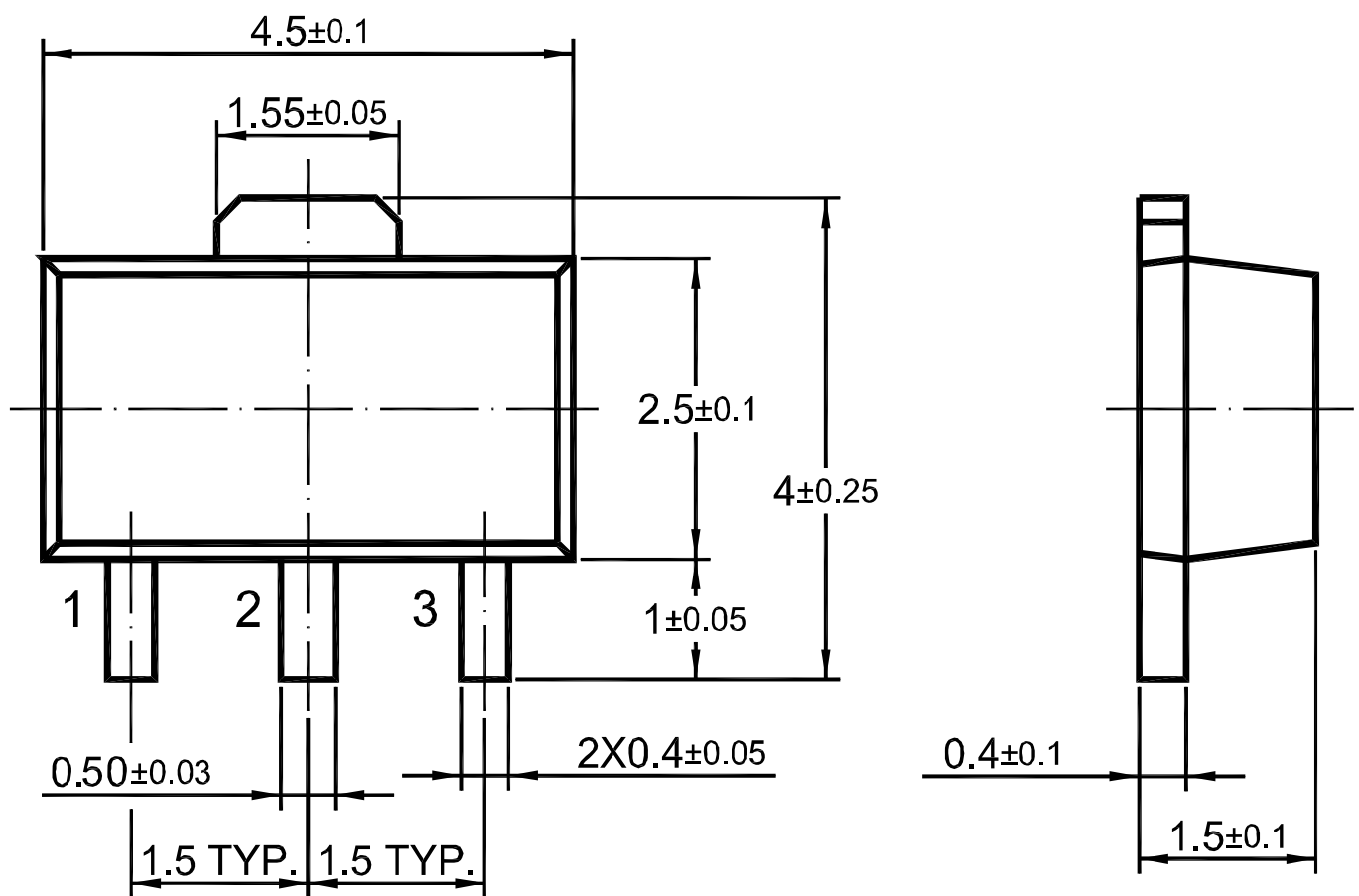
Dimensions in mm



Package Outline

SOT-89

Dimensions in mm



Package Outline

SOT-23-5

Dimensions in mm

